# XN01509 (XN1509)

### Silicon NPN epitaxial planer transistor

#### For high-frequency amplification

#### Features

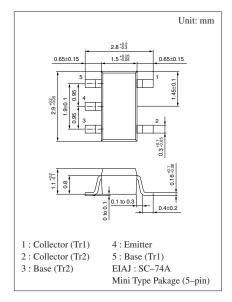
- Two elements incorporated into one package. (Emitter-coupled transistors)
- Reduction of the mounting area and assembly cost by one half.

#### Basic Part Number of Element

• 2SC4561 × 2 elements

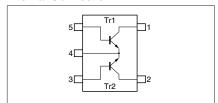
#### Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Ratings	Unit	
Rating of element	Collector to base voltage	$V_{CBO}$	50	V	
	Collector to emitter voltage	$V_{CEO}$	50	V	
	Emitter to base voltage	$V_{EBO}$	5	V	
	Collector current	$I_{C}$	50	mA	
Overall	Total power dissipation	$P_{T}$	200	mW	
	Junction temperature	$T_{j}$	150	°C	
	Storage temperature	$T_{stg}$	-55 to +150	°C	



#### Marking Symbol: AN

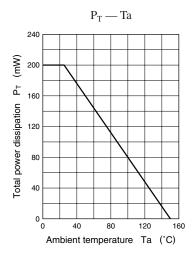
#### Internal Connection

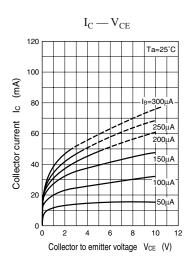


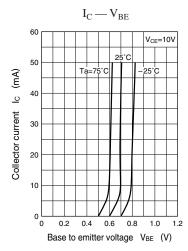
#### Electrical Characteristics (Ta=25°C)

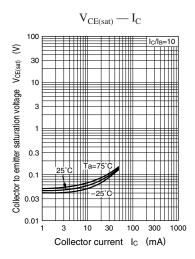
Parameter	Symbol	Conditions	min	typ	max	Unit
Collector to base voltage	V <sub>CBO</sub>	$I_C = 10 \mu A, I_E = 0$	50			V
Collector to emitter voltage	V <sub>CEO</sub>	$I_C = 1 \text{mA}, I_B = 0$	50			V
Emitter to base voltage	V <sub>EBO</sub>	$I_{\rm E} = 10 \mu A, I_{\rm C} = 0$	5			V
Collector cutoff current	$I_{CBO}$	$V_{CB} = 10V, I_{E} = 0$			0.1	μΑ
Collector cutoff current	$I_{CEO}$	$V_{CE} = 10V, I_B = 0$			100	μΑ
Forward current transfer ratio	h <sub>FE</sub>	$V_{CE} = 10V, I_C = 2mA$	200		500	
Forward current transfer h <sub>FE</sub> ratio	h <sub>FE</sub> (small/large)*1	$V_{CE} = 10V, I_{C} = 2mA$	0.5	0.99		
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>	$I_{C} = 10\text{mA}, I_{B} = 1\text{mA}$		0.06	0.3	V
Transition frequency	$f_T$	$V_{CB} = 10V$ , $I_{E} = -2mA$ , $f = 200MHz$		250		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 10V, I_E = 0, f = 1MHz$		1.5		pF

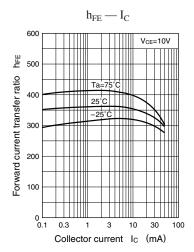
<sup>\*1</sup> Ratio between 2 elements

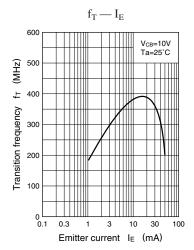


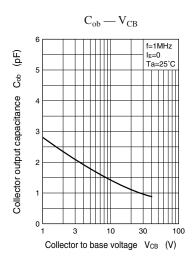












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